

**General Description**

The CMSA6404 combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

**Features**

- Low ON-resistance
- 100% avalanche tested
- ESD protected
- Small Footprint (5x6mm) for Compact Design
- RoHS Compliant

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current	85	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current	67	A
$I_{DM}$	Pulsed Drain Current	280	A
EAS	Single Pulse Avalanche Energy <sup>1</sup>	334	mJ
$P_D @ T_c = 25^\circ C$	Total Power Dissipation	83	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Steady-State) <sup>2,3</sup>	---	55	°C/W
$R_{\theta JC}$	Thermal Resistance Junction -Case (Steady-State)	---	1.5	°C/W

**Product Summary**

BVDSS	RDS(on)	ID
30V	2.3mΩ	85A

**Applications**

- DC/DC Converters in Computing, Servers, and POL
- Isolated DC/DC Converters in Telecom and Industrial

**DFN-8 5x6 Pin Configuration**

Type	Package	Marking
CMSA6404	DFN-8 5*6	CMSA6404

Electrical Characteristics ( $T_J=25^\circ\text{C}$  , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	1.9	2.3	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=20\text{A}$	---	2.4	3	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D =250\mu\text{A}$	1.0	---	2.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 16\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 10$	$\mu\text{A}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=20\text{A}$	---	75	---	S
$Q_g$	Total Gate Charge	$V_{\text{DS}}=15\text{V}$ , $I_D=20\text{A}$	---	71	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	10	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	16	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_L=0.75\Omega$ $R_{\text{GEN}}=3\Omega$	---	10	---	$\text{ns}$
$T_r$	Rise Time		---	7	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	76	---	
$T_f$	Fall Time		---	18	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	4300	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	700	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	430	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Diode continuous forward current	$V_G=V_D=0\text{V}$ , Force Current	---	---	85	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	280	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_F=20\text{A}$ , $T_J=25^\circ\text{C}$	---	0.79	1.2	V

Note:

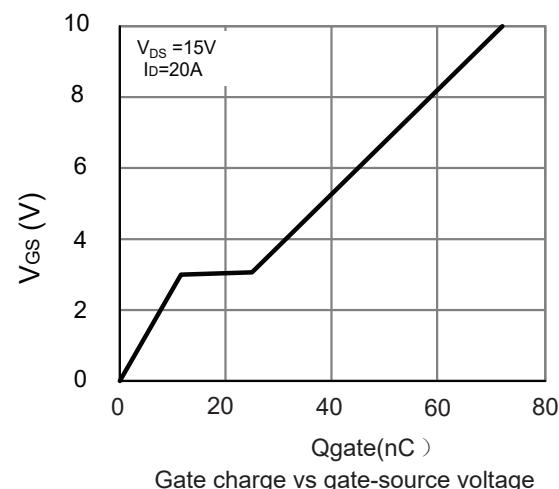
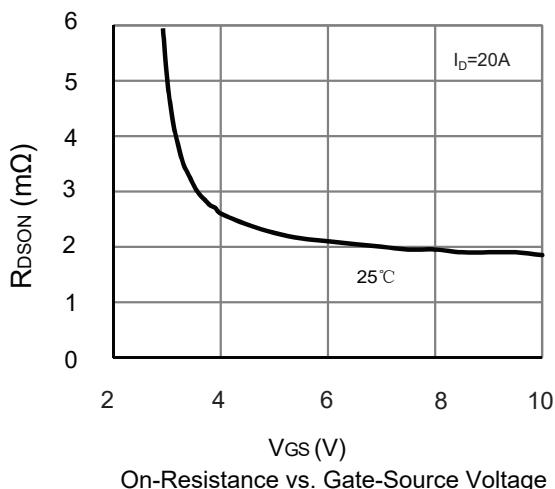
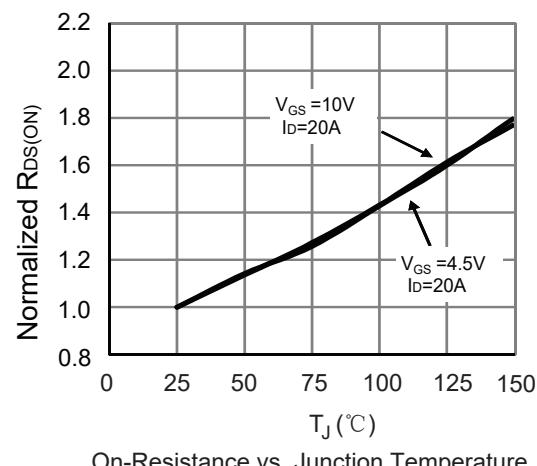
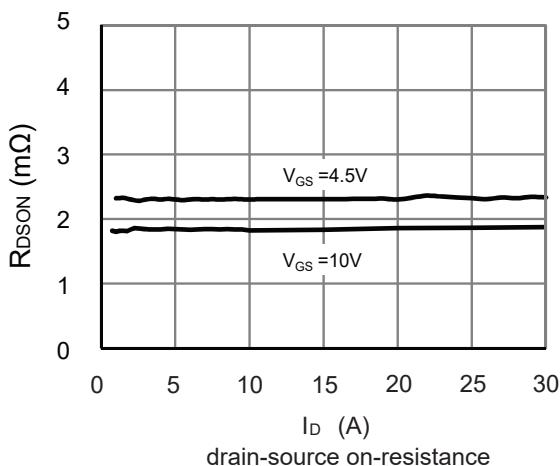
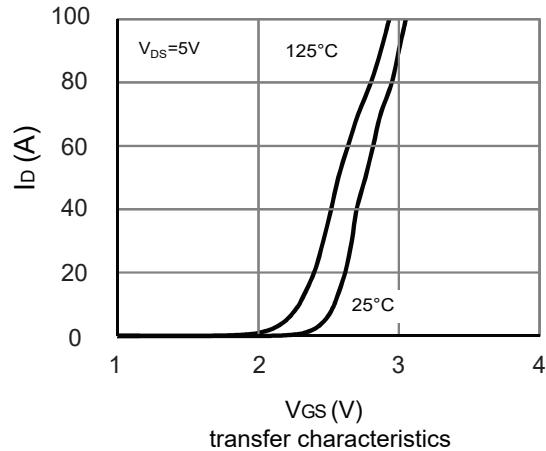
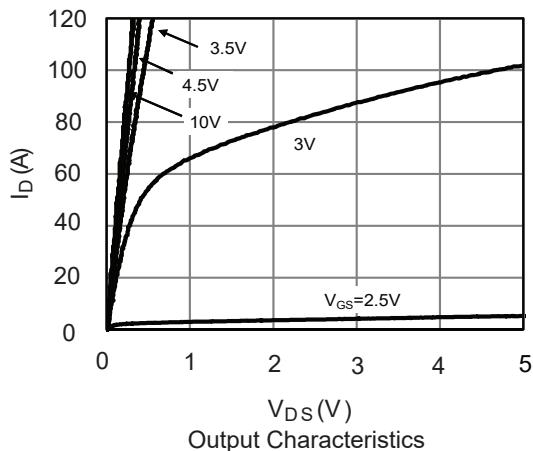
- The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=20\text{V}$  ,  $V_{\text{GS}}=10\text{V}$  ,  $L=0.5\text{mH}$  ,  $I_{\text{AS}}=28\text{A}$ .
- The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The Power dissipation  $P_{\text{DSM}}$  is based on  $R_{\theta JA}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design, and the maximum temperature of  $150^\circ\text{C}$  may be used if the PCB allows it.
- The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to case  $R_{\theta JC}$  and case to ambient.

This product has been designed and qualified for the consumer market.

Cmos assumes no liability for customers' product design or applications.

Cmos reserves the right to improve product design ,functions and reliability without notice.

## Typical Characteristics



## Typical Characteristics

